

ABSTRACT

5 A brittle substrate cutting system according to the
present invention includes a scribing apparatus including
a scribing line forming means for forming a scribing line
on a first surface of a brittle substrate; and a breaking
apparatus for breaking the brittle substrate along the
10 scribing line, wherein the breaking apparatus includes a
first pressing controlling means for moving a pressing force
upon a second surface of the brittle substrate opposing the
first surface of the brittle substrate along the scribing
line while the first surface of the brittle substrate is
held.